

CLAIM AMENDMENTS

1. (Currently Amended) A package for ~~Optical~~ an optical semiconductor device comprising;

a stem having an under surface, an upper surface, a mount to be mounted, with an optical semiconductor device, on the upper surface, at least one ~~or more~~ through holes hole penetrating from the upper surface to the under surface, and

a lead terminal for signal supply penetrating one of ~~said the~~ through holes ~~so as to be~~ and insulated by an insulator from the stem, wherein ~~said the~~ upper surface has an earth conductor adjacent to the lead terminal for signal supply ~~projected~~ projecting from the upper surface.

2. (Currently Amended) The package for ~~Optical~~ an optical semiconductor devices according to claim 1₁, wherein ~~said the~~ earth conductor ~~is enclosing~~ encloses at least part of ~~said the~~ lead terminal for signal supply ~~projected~~ projecting from the upper surface.

3. (Currently Amended) The package for ~~Optical~~ an optical semiconductor device according to claim 2₁, wherein ~~said the~~ earth conductor ~~is surrounding a range of~~ surrounds at least 150 degrees ~~or more centering on the~~ around a center axis of ~~said the~~ lead terminal for signal supply ~~projected~~ projecting from the upper surface.

4. (Currently Amended) The package for ~~Optical~~ an optical semiconductor device according to claim 1₁, wherein ~~said the~~ earth conductor ~~is formed with~~ includes the mount monolithically.

5. (Currently Amended) The package for ~~Optical~~ an optical semiconductor device according to claim 1₁, wherein ~~said the~~ earth conductor overlaps with ~~said the~~ insulator.

6. (Currently Amended) The package for ~~Optical~~ an optical semiconductor device according to claim 1₁, ~~wherein~~ including a dielectric member ~~is placed~~ located between ~~said the~~ earth conductor and ~~said the~~ lead terminal for signal supply.

7. (Currently Amended) The package for ~~Optical~~ an optical semiconductor device according to claim 1₁, ~~wherein~~ including earth electrode terminals ~~are arranged in both~~ on

~~opposite~~ sides of ~~said the~~ terminal for signal supply ~~projected~~ projecting from the under surface of the ~~above-mentioned~~ stem.

8. (Currently Amended) The package for ~~Optical~~ an optical semiconductor device according to claim 1~~;~~₂ wherein ~~said the~~ earth electrode terminals are monolithically integrated with ~~said the~~ stem.

9. (Currently Amended) The package for ~~Optical~~ an optical semiconductor device according to claim 1~~;~~₃ further comprising a second lead terminal for signal supply pairing with ~~said the~~ lead terminal for signal supply.

10. (Currently Amended) The package for ~~Optical~~ an optical semiconductor device according to claim 1~~;~~₄ wherein ~~said the~~ earth conductor ~~is formed with said~~ includes the mount monolithically and ~~said the~~ mount is attached ~~on said~~ to the stem so that ~~said the~~ earth conductor overlaps ~~with said the~~ insulator.

11. (Currently Amended) The package for ~~Optical~~ an optical semiconductor device according to claim 1~~;~~₅ wherein ~~said the~~ mount and ~~said the~~ stem are produced by press processing, respectively.

12. (Currently Amended) The package for ~~Optical~~ an optical semiconductor device according to claim 10~~;~~₆ wherein a distance between ~~said the~~ earth ~~conductors~~ conductor and ~~said the~~ lead terminal for signal supply ~~is set so that~~ provides a characteristic impedance of a transmission line constituted ~~with said by the~~ lead terminal for signal supply ~~projected~~ projecting from the upper surface of ~~said the~~ stem ~~is set to~~ of no more than 60 ohms ~~or less~~.

13. (Currently Amended) The package for ~~Optical~~ an optical semiconductor device according to claim 10~~;~~₇ wherein a distance between ~~said the~~ earth ~~conductors~~ conductor and ~~said the~~ lead terminal for signal supply is no more than 0.175mm ~~or less~~.

14. (Currently Amended) The package for ~~Optical~~ an optical semiconductor device according to claim 10~~;~~₈ further comprising a guide for positioning ~~said the~~ mount on the upper surface of ~~said the~~ stem.

15. (Currently Amended) The package for ~~Optical~~ an optical semiconductor device according to claim ~~10,~~ 12, wherein a tip portion of ~~said the~~ lead terminal for signal supply is deformed so that ~~said the~~ characteristic impedance of said transmission line ~~become small~~ is reduced.

16. (Currently Amended) The package for ~~Optical~~ an optical semiconductor device according to claim ~~15,~~ 15₂, wherein said lead terminal for signal supply ~~is formed in~~ has a cylinder shape and ~~said the~~ tip portion is deformed by crushing the cylinder shape into a flat portion.

17. (Currently Amended) The package for ~~Optical~~ an optical semiconductor device according to claim ~~15,~~ 15₂, wherein a face of the earth conductor surrounding ~~said the~~ lead terminal is crooked along with ~~said deformed the~~ tip portion of said lead terminal for signal supply.

18. (Currently Amended) The package for ~~Optical~~ an optical semiconductor device according to claim ~~10,~~ 10₂, wherein ~~said the~~ mount has a step at a corner ~~thereof~~ in the ~~lap~~ portion of said earth conductor ~~and said overlapping the~~ insulator so that ~~said the~~ earth conductor ~~is~~ does not directly contact the ~~direct above-mentioned~~ insulator.

19. (Currently Amended) The package for ~~Optical~~ an optical semiconductor device according to claim ~~10,~~ 10₂, wherein ~~said the~~ mount is ~~placed~~ located on the upper surface of ~~said the stem with and including a plinth between them the mount and the stem in the lap portion of said the earth conductor and said overlapping the~~ insulator so that ~~said the~~ earth conductor ~~is~~ does not directly contact the ~~direct above-mentioned~~ insulator.

20. (Currently Amended) The package for ~~Optical~~ an optical semiconductor device according to claim ~~10,~~ 10₂, wherein ~~said the~~ mount has a corner ~~made in with a circumference~~ circumferential shape in the ~~lap~~ portion of ~~said the~~ earth conductor ~~and said overlapping the~~ insulator so that ~~said the~~ earth conductor ~~is~~ does not directly contact the ~~direct above-mentioned~~ insulator.